

## DRIE SiC Usage Policy

- ✚ Allowed etch materials: GaN, AlN, InN, and their alloys (on the top surface only).
- ✚ Allowed substrates: SiC and GaN.
- ✚ Etching of SiC substrate as part of approved recipes.
- ✚ Only Ni masks are permitted. No other mask materials are allowed.
- ✚ Gold (Au) is strictly prohibited in any form.
- ✚ Access to the tool is restricted — only authorized staff may operate the system. No training will be provided to general users.
- ✚ Only fixed and pre-approved recipes may be used.
- ✚ Custom recipe development is not permitted.
- ✚ Blanket etching is not allowed.
- ✚ Only selective area etching is permitted, with substrate coverage limited to <10%.
- ✚ Only small samples ( $\leq 1 \text{ inch} \times 1 \text{ inch}$ ) may be processed.
- ✚ All samples must be clearly labelled with details of the material, substrate, and mask.
- ✚ Users must ensure that no prohibited materials (e.g., gold or unapproved masks) are present on the sample.
- ✚ Any violation of the above policies including presence of gold, unapproved masks, blanket etching, or unauthorized tool use will result in suspension of access.
- ✚ Repeated violations may lead to permanent revocation of lab access.